



## Final Product Change Notification

201609012F01

**Issue Date:** 19-Jan-2018  
**Effective Date:** 19-Apr-2018

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online



# QUALITY

### Change Category

- |  |  |  |   |   |
|--|--|--|---|---|
| <input type="checkbox"/> Wafer Fab Process   | <input type="checkbox"/> Assembly Process              | <input type="checkbox"/> Product Marking           | <input type="checkbox"/> Test Location  | <input type="checkbox"/> Design                         |
| <input type="checkbox"/> Wafer Fab Materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification  | <input type="checkbox"/> Test Process   | <input type="checkbox"/> Errata                         |
| <input type="checkbox"/> Wafer Fab Location  | <input checked="" type="checkbox"/> Assembly Location  | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |

**SPC5632/3/4M Assembly Site Expansion From NXP-ATKL To ASE Chung Li For The 144LQFP**

### Details of this Change

NXP Semiconductors announces the Assembly site expansion for SPC5632M, SPC5633M and SPC5634M (144LQFP) associated with this notification from the current NXP-ATKL, Kuala Lumpur, Malaysia assembly facility to the ASE, Chung Li, Taiwan R.O.C assembly facility.

The change in assembly site also include change in mold compound, die attach, copper wire and lead frame paddle size. A CofDC comparison is attached to this notification to provide detailed comparisons between the bill of materials.

Assembly site expansion was successfully qualified adhering to NXP specifications. Corresponding ZVEI Delta Qualification Matrix ID: SEM-PA-03, SEM-PA-07, SEM-PA-08, SEM-PA-11 and SEM-PA-18.

Please see attached files for additional details.

### Why do we Implement this Change

Qualification of the ASE, Chung Li, Taiwan R.O.C is required for manufacturing flexibility and customer

supply assurance.

### Identification of Affected Products

There is no change to orderable part number.

Change in package trace code is explained under the 'Remarks' section below.

## Product Availability

### Sample Information

Samples are available from 26-Jan-2018

Below are the sample part numbers that will be made available.

- KPC5634MF1AMLQ80

- KC5634MF1AMLQ80R

- KPC5634MF2AMLQ80

- KC5634MF2AMLQ80R

### Production

Planned first shipment 30-Apr-2018

## Impact

no impact to the product's functionality anticipated.

### Disposition of Old Products

Assembly site expansion. No Depletion of Inventory required.

## Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 18-Feb-2018.

## Remarks

The assembly site, among other information, is reflected in the package trace code.

The format for the NXP standard trace code: AWLYYWW is the following:

A=Assembly Site, WL=Wafer Lot, YY=Year, WW=Work Week.

The current assembly site marking for site 1 (ATKL) is A = Q

The marking for proposed assembly site 2 (ASECL) is A= X

## Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

**Name** Choon Hong Lau

**Position** Product Engineer

**e-mail address** choonhong.lau@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

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NXP Semiconductors

High Tech Campus, 5656 AG Eindhoven, The Netherlands

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**Affected Part Number**

SPC5634MF2MLQ80